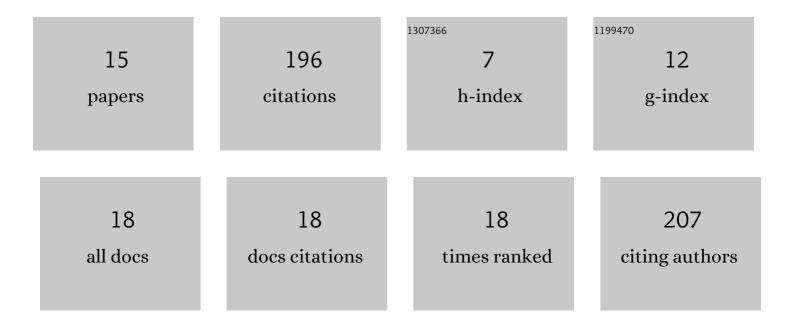
## Amirali Toossi

List of Publications by Year in descending order

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AMIRALI TOOSSI

#	Article	IF	CITATIONS
1	A Mass-Producible Washable Smart Garment with Embedded Textile EMG Electrodes for Control of Myoelectric Prostheses: A Pilot Study. Sensors, 2022, 22, 666.	2.1	15
2	3Dâ€Knit Dry Electrodes using Conductive Elastomeric Fibers for Longâ€Term Continuous Electrophysiological Monitoring. Advanced Materials Technologies, 2022, 7, .	3.0	15
3	Overground gait kinematics and muscle activation patterns in the Yucatan mini pig. Journal of Neural Engineering, 2022, 19, 026009.	1.8	5
4	Neurovascular pathology following traumatic spinal cord injury. , 2022, , 119-132.		0
5	Variety Is the Spice of Life: Positive and Negative Effects of Noise in Electrical Stimulation of the Nervous System. Neuroscientist, 2021, 27, 529-543.	2.6	3
6	Comparative neuroanatomy of the lumbosacral spinal cord of the rat, cat, pig, monkey, and human. Scientific Reports, 2021, 11, 1955.	1.6	46
7	Novel innovations in cell and gene therapies for spinal cord injury. F1000Research, 2020, 9, 279.	0.8	33
8	Functional organization of motor networks in the lumbosacral spinal cord of non-human primates. Scientific Reports, 2019, 9, 13539.	1.6	13
9	Brachial Artery Catheterization in Swine. Journal of Visualized Experiments, 2019, , .	0.2	2
10	Effect of anesthesia on motor responses evoked by spinal neural prostheses during intraoperative procedures. Journal of Neural Engineering, 2019, 16, 036003.	1.8	11
11	Ultrasound-guided spinal stereotactic system for intraspinal implants. Journal of Neurosurgery: Spine, 2018, 29, 292-305.	0.9	18
12	Gastric and Cardio-Vascular Muscle Stimulation. Series on Bioengineering and Biomedical Engineering, 2017, , 870-887.	0.1	0
13	Mechanically Stable Intraspinal Microstimulation Implants for Human Translation. Annals of Biomedical Engineering, 2017, 45, 681-694.	1.3	25
14	Efficient Microwave Susceptor Design for Localized Heating on Substrate. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 570-578.	1.4	6
15	Microwave susceptor design for wafer bonding applications. , 2012, , .		2